# 2SD1271A

## Silicon NPN epitaxial planar type

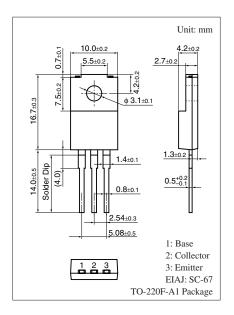
### For power switching

#### ■ Features

- Low collector-emitter saturation voltage V<sub>CE(sat)</sub>
- Satisfactory linearity of forward current transfer ratio h<sub>FE</sub>
- Large collector current I<sub>C</sub>
- Full-pack package which can be installed to the heat sink with one screw

### ■ Absolute Maximum Ratings $T_C = 25$ °C

V
V
V
A
A
W
°C
°C



## ■ Electrical Characteristics $T_C = 25$ °C $\pm 3$ °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = 10 \text{ mA}, I_B = 0$	100			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 100 \text{ V}, I_E = 0$			10	μΑ
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = 5 \text{ V}, I_{C} = 0$			50	μΑ
Forward current transfer ratio	h <sub>FE1</sub>	$V_{CE} = 2 \text{ V}, I_{C} = 0.1 \text{ A}$	45			_
	h <sub>FE2</sub> *	$V_{CE} = 2 \text{ V}, I_{C} = 3 \text{ A}$	60		260	
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = 5 \text{ A}, I_B = 0.25 \text{ A}$			0.5	V
Base-emitter saturation voltage	V <sub>BE(sat)</sub>	$I_C = 5 \text{ A}, I_B = 0.25 \text{ A}$			1.5	V
Transition frequency	$f_T$	$V_{CE} = 10 \text{ V}, I_{C} = 0.5 \text{ A}, f = 10 \text{ MHz}$		30		MHz
Turn-on time	t <sub>on</sub>	$I_C = 1 A$ , $I_{B1} = 0.1 A$ , $I_{B2} = -0.1 A$		0.5		μs
Storage time	t <sub>stg</sub>	$V_{CC} = 50 \text{ V}$		2.5		μs
Fall time	t <sub>f</sub>			0.4		μs

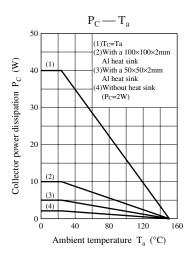
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

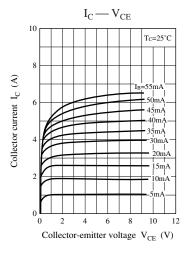
#### 2. \*: Rank classification

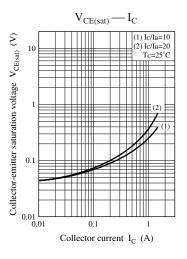
Rank	R	Q	Р
h <sub>FE2</sub>	60 to 120	90 to 180	130 to 260

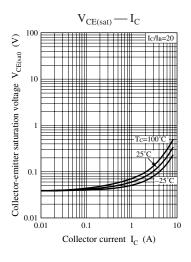
Publication date: April 2003 SJD00302AED 1

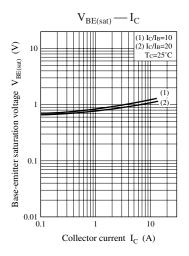
## **Panasonic**

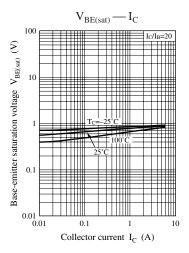


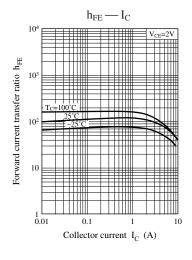


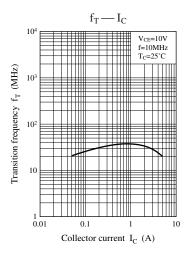


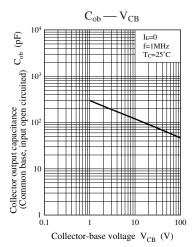




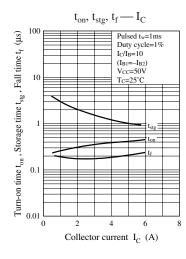


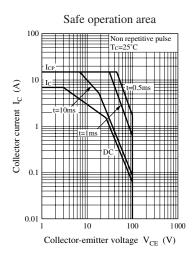


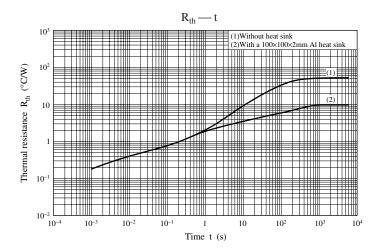




2 SJD00302AED







SJD00302AED 3

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